DIL-Sockets partial assembled Series 110
TO-Sockets

1. DIL-Sockets partial assembled, f.e. for Oscillators and relays.
2. TO-Socket with precision round contacts

Highest contact safety due to 4 multi-finger contact made of Beryllium copper with homogeneous gold plating.

For PCB's up to 2.0 mm thickness.

No capillary action during soldering due to screened inner contact. No fluxing medium or tin in the contact area.

Contact clip Beryllium copper
Surface Nickel 2 - 3 µm, gold 0.75 µm

Sleeve typical CuZn alloy turned
Surface Nickel 2 - 3 µm, tin 5 µm (Sn100)

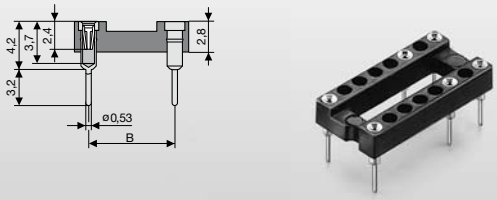
Insulator body Thermoplastic polyester glass-fibre reinforced,self-extinguishing rated UL94V0

Operation temperature -55 up to +125 °C

Solder temperature from 235°C acc. IEC 68-2-54 Ta
Solder head resistance up to 260°C 10 sec. Series 110, 5 sec. TO-Socket acc. IEC 68-2-20 Tb

Contact depth 1.9 respectively 2.4 mm by safe contact making
Accepted diameter 0.4 - 0.56 mm
Rated voltage 100 V_{RMS}/150 VDC
Insulation resistance $>10^{10}$ Ω
Contact resistance ≤ 10 mΩ
Current carrying capacity per contact 1 A
Moisture sensibility level (MSL) J-STD-020C Level 1
RoHS-conform

Series 110 partial assembled
For pin
Ø 0,4 bis 0,56 mm
▱ 0,25 x 0,45 mm



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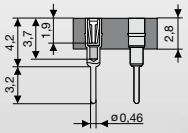
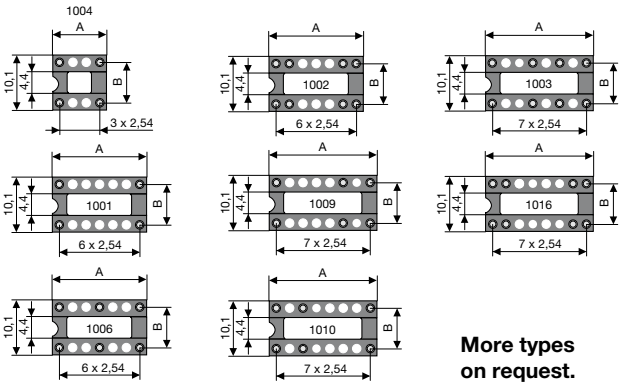
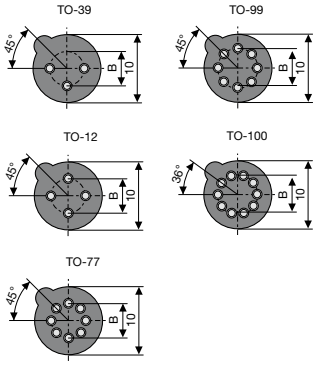




More types on request.



		Sleeve		5 µm tin
		Clip		0.75 µm gold
A	**B**	**Pins X**	**Y**	**PU**	**Order No.**
10.1	7.62	**8**	**4**	52	110-83-300-1004
17.7	7.62	**14**	**4**	29	110-83-300-1001
17.7	7.62	**14**	**6**	29	110-83-300-1006
17.7	7.62	**14**	**8**	29	110-83-300-1002
20.3	7.62	**16**	**6**	25	110-83-300-1009
20.3	7.62	**16**	**6**	25	110-83-300-1010
20.3	7.62	**16**	**8**	25	110-83-300-1003
20.3	7.62	**16**	**8**	25	110-83-300-1016

X = Insulator body/Y = Pins

		Sleeve		5 µm tin
		Clip		0.75 µm gold
Type	**B**	**Pins**	**PU**	**Order No.**
TO-39	5.08	**3**	50	917-83-103-41-005
TO-12	5.08	**4**	50	917-83-104-41-005
TO-77	5.08	**8**	50	917-83-108-41-005
TO-99	5.84	**8**	50	917-83-208-41-005
TO-100	5.84	**10**	50	917-83-210-41-005

PU = Packaging Unit